imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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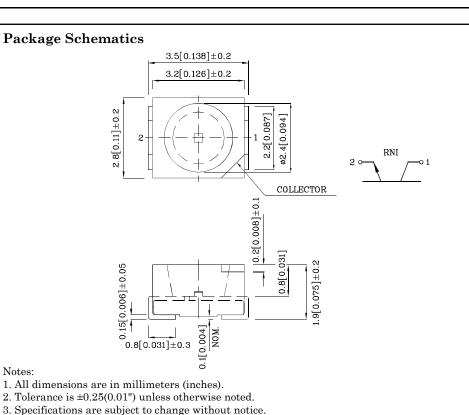
Part Number: XZRNI45S

3.5x2.8mm PHOTOTRANSISTOR

Features

- Long life and robust package
- Standard Package: 2000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- \bullet RoHS compliant





Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Condiction
VBR CEO	Collector-to-Emitter Breakdown Voltage	30			V	Ic=100µA Ee=0mW/cm ²
VBR ECO	Emitter-to-Collector Breakdown Voltage	5			V	IE=100µA Ee=0mW/cm ²
VCE(SAT)	Collector-to-Emitter Saturation Voltage			0.8	V	IC=2mA Ee=20mW/cm ²
Iceo	Collector Dark Current			100	nA	VCE=10V Ee=0mW/cm ²
TR	Rise Time (10% to 90%)		15		μs	Vce=5V Ic=1mA RL=1KΩ
$T_{\rm F}$	Fall Time (90% to 10%)		15		μs	
I(ON)	On State Collector Current	0.2	0.4		mA	$V_{CE}=5V$ Ee=1mW/cm ² λ =940nm

Absolute Maximum Ratings at TA=25°C

Parameter	Maximum Ratings		
Collector-to-Emitter Voltage	30V		
Emitter-to-Collector Voltage	$5\mathrm{V}$		
Power Dissipation at (or below) 25°C Free Air Temperature	100mW		
Operating / Storage Temperature Range	-40°C To +85°C		

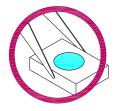
A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)



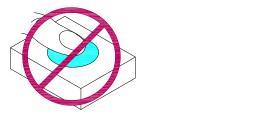
Handling Precautions

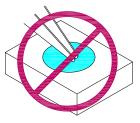
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

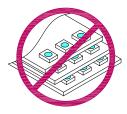


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

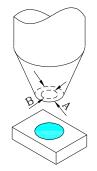




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.

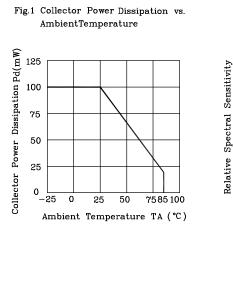


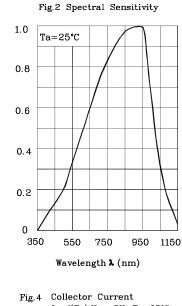
4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

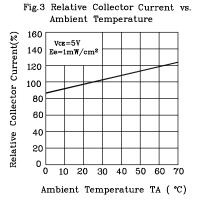


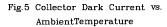
5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

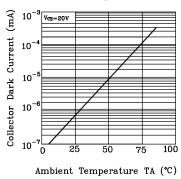


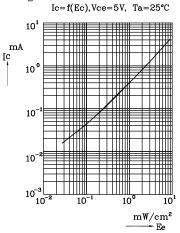


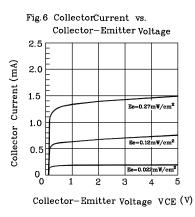




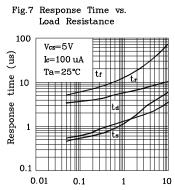








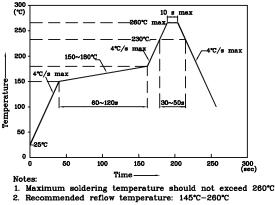


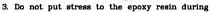


Load Resistance RL(k**Q**)

***** LED is recommended for reflow soldering and soldering profile is shown below.

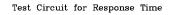
Reflow Soldering Profile for SMD Products (Pb-Free Components)

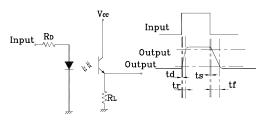




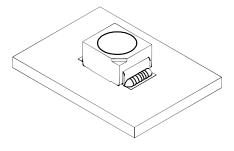
high temperatures conditions

Tape Specification (Units : mm)

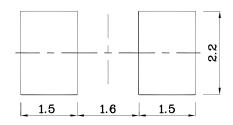


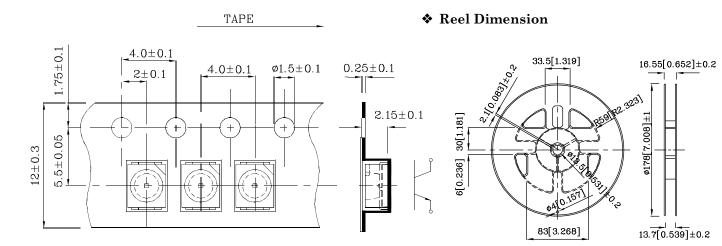


✤ The device has a single mounting surface. The device must be mounted according to the specifications.



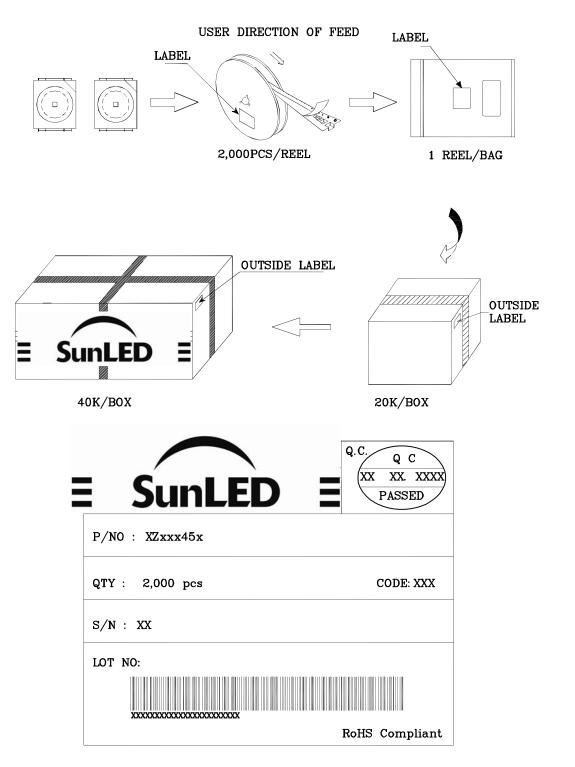
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)







PACKING & LABEL SPECIFICATIONS



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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
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Oct 12, 2016